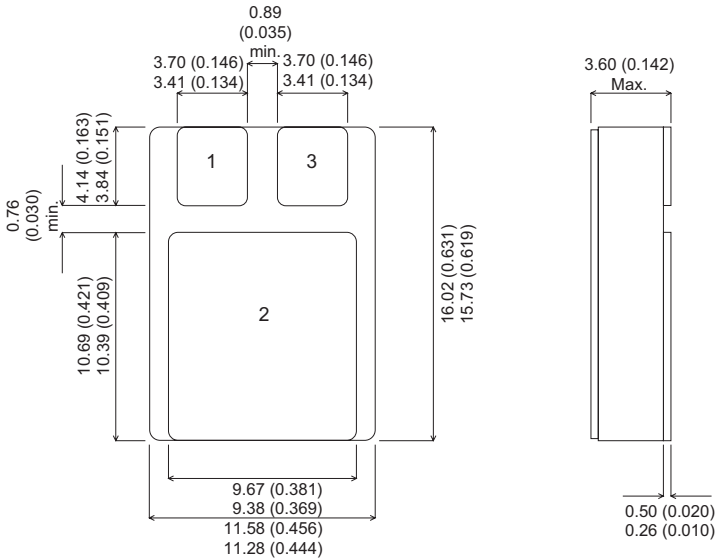


MECHANICAL DATA

Dimensions in mm



SMD1 (TO-276AB) CERAMIC PACKAGE

**DUAL SCHOTTKY
 BARRIER DIODE
 IN CERAMIC SURFACE
 MOUNT PACKAGE FOR
 HI-REL APPLICATIONS**

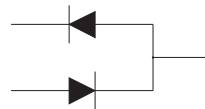
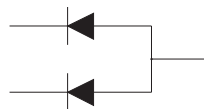
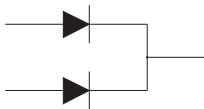
FEATURES

- HERMETIC CERAMIC PACKAGE
- AVAILABLE IN COMMON CATHODE, COMMON ANODE AND SERIES VERSIONS
- SCREENING OPTIONS AVAILABLE
- OUTPUT CURRENT 30A
- LOW V_F
- LOW LEAKAGE

Common Cathode
SB30-45M

Common Anode
SB30-45A

Series Connection
SB30-45R



1 = A₁ Anode 1
 2 = K Cathode
 3 = A₂ Anode 2

1 = K₁ Cathode 1
 2 = A Anode
 3 = K₂ Cathode 2

1 = K₁ Cathode 1
 2 = Centre Tap
 3 = A₂ Anode

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^\circ C$ unless otherwise stated)

V_{RRM}	Peak Repetitive Reverse Voltage	45V
V_{RSM}	Peak Non-Repetitive Reverse Voltage	45V
V_R	Continuous Reverse Voltage	45V
$I_{F(AV)}$	Maximum Average Forward Current	30A
I_{FSM}	Peak Non-Repetitive Surge Current at 50Hz (per leg)	245A
T_{STG}	Storage Temperature Range	-55°C to 150°C
T_J	Maximum Operating Junction Temperature	150°C

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ELECTRICAL CHARACTERISTICS ($T_{CASE} = 25^{\circ}C$ unless otherwise stated)

Parameter		Test Conditions		Min.	Typ.	Max.	Unit
V_F	Maximum Forward Voltage Drop (per diode)*	$I_F = 15A$	$T_J = 25^{\circ}C$			0.6	V
		$I_F = 30A$	$T_J = 25^{\circ}C$			0.75	
		$I_F = 15A$	$T_J = 125^{\circ}C$			0.55	
		$I_F = 30A$	$T_J = 125^{\circ}C$			0.7	
I_R	Reverse Maximum Leakage Current (per diode)*	$V_R = 45V$	$T_J = 25^{\circ}C$			2	mA
		$V_R = 45V$	$T_J = 125^{\circ}C$			75	
C_d	Junction Capacitance	$V_R = 5 V$	$f = 1 MHz$		900		pF

*Pulse test $t_p=300\mu s$ $\delta \leq 2\%$

Parameter			Unit
$R_{TH(j-c)}$	Maximum Thermal Resistance Junction To Case	(per package)	1.3 $^{\circ}C/W$
$R_{TH(j-c)}$	Maximum Thermal Resistance Junction To Case	(per diode)	2.4 $^{\circ}C/W$

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